

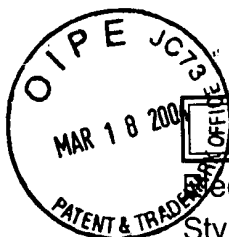
Electronic Filing System (EFS) Data
Electronic Patent Application Submission
USPTO Use Only

EFS ID: 57326
Application ID: 10708400
Title of Invention: Heat Sink Fan and Method for
Manufacturing Heat Sink That Is
Used For the Heat Sink Fan
First Named Inventor: Takaya Otsuki
Domestic/Foreign Application: Domestic Application
Filing Date: 2004-03-01
Effective Receipt Date: 2004-03-18
Submission Type: Information Disclosure
Statement
Filing Type:
Confirmation number: 2399
Attorney Docket Number: 18.017-AG




Total Fees Authorized:

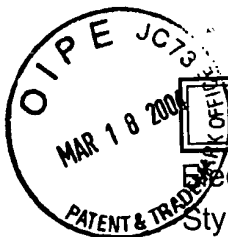
Digital Certificate Holder: cn=James Judge,ou=Registered Attorneys,ou=Patent and Trademark
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TRANSMITTAL

Electronic Version v1.1
Stylesheet Version v1.1.0

Title of Invention	Heat Sink Fan and Method for Manufacturing Heat Sink That Is Used For the Heat Sink Fan									
Application Number: 10/708400 										
Date: 2004-03-01										
First Named Applicant: Mr. Takaya Otsuki										
Confirmation Number: 2399										
Attorney Docket Number: 18.017-AG										
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<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>Mr. James Judge Registered Number: 42,701</td><td>jjJUDGE</td><td>Agent</td></tr></tbody></table>			Submitted by:	Elec. Sign.	Sign. Capacity	Mr. James Judge Registered Number: 42,701	jjJUDGE	Agent		
Submitted by:	Elec. Sign.	Sign. Capacity								
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<table><tr><td>Documents being submitted</td><td>Files</td></tr><tr><td>us-ids</td><td>ND017IDS-usidst.xml</td></tr><tr><td></td><td>us-ids.dtd</td></tr><tr><td></td><td>us-ids.xsl</td></tr></table>			Documents being submitted	Files	us-ids	ND017IDS-usidst.xml		us-ids.dtd		us-ids.xsl
Documents being submitted	Files									
us-ids	ND017IDS-usidst.xml									
	us-ids.dtd									
	us-ids.xsl									
Comments										



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18
Stylesheet Version v18.0

Title of
Invention

Heat Sink Fan and Method for Manufacturing Heat Sink That
Is Used For the Heat Sink Fan

Application Number: 10/708400
Confirmation Number: 2399
First Named Applicant: Takaya Otsuki
Attorney Docket Number: 18.017-AG
Search string: (5484013 or 5794685 or 6302189 or 6392885
or 6415852 or 6419007 or 6520250 or
20030024688 or 20030024693 or
20030048612).pn.



US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	5484013	1996-01-16	Morikawa et al.	A	165	80.3
	2	5794685	1998-08-18	Dean	A	165	121
	3	6302189	2001-10-16	Lin et al.	B1	165	80.3
	4	6392885	2002-05-21	Lee et al.	B1	361	697
	5	6415852	2002-07-09	Lo	B1	165	80.3
	6	6419007	2002-07-16	Ogawara et al.	B1	165	80.3
	7	6520250	2003-02-18	Lee et al.	B2	165	121

US Published Applications

Note: Applicant is not required to submit a paper copy of cited US Published Applications

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
	1	20030024688	2003-02-06	Dowdy et al.	A1	165	80.3
	2	20030024693	2003-02-06	Petty et al.	A1	165	121
	3	20030048612	2003-03-13	Carter et al.	A1	361	718

Remarks



Note: Remarks are not for responding to an office action.

Among the U.S. patent documents submitted hereby, Cite Nos. 1 and 6 are discussed in the "Background of the Invention" section under "Description of the Prior Art" in the specification in the present application.

Signature

Examiner Name	Date